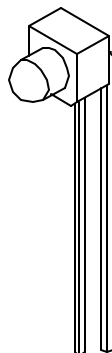
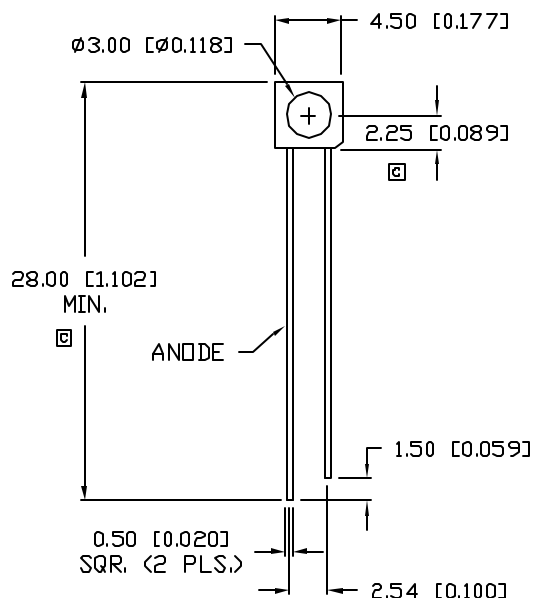
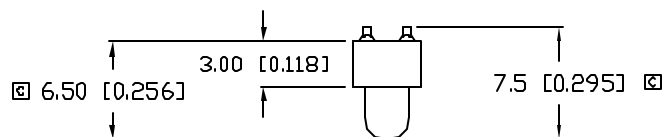


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PART NUMBER  
SSF-LX3P74YD-99

REV.  
E

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	ADDED AXIAL INTENSITY	2.2.94
B	UPDATED SAFE OPERATING SPECS.	11.16.94
C	ADDED AND CORRECTED DIMS.	5.10.95
D	E.C.N. #10BRDR.	4.2.98
E	E.C.N. #10BRDR. & REDRAWN IN 3D.	7.18.01



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		25		mcad	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^{\circ}\text{C}$

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^{\circ}\text{C}$	-1.2	mW/ $^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$
SOLDERING TEMP.	+260	$^{\circ}\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=<sup>+DECIMAL PRECISION</sup>-0.00 <sup>MAX.=+0.00</sup>-DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. E	PART NUMBER SSF-LX3P74YD-99
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T-3mm (T-1) ALL EPOXY RIGHT ANGLE INDICATOR,  
585nm YELLOW LED, YELLOW DIFFUSED.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 6.29.90
			PAGE: 1 OF 1
			SCALE: N/A